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General Information	
Series	SMD Comm COG HV
Style	SMD Chip
Description	SMD, MLCC, Ultra-Stable, Low Loss, Class I
Features	Ultra-Stable, Low Loss, Class I
RoHS	Yes
Termination	Tin
Marking	false
AEC-Q200	No
Typical Component Weight	1.06 g
Shelf Life	78 Weeks
MSL	1

Dimensions	
Chip Size	3640
L	9.1mm +/-0.4mm
W	10.2mm +/-0.4mm
T	2.5mm +/-0.20mm
S	6.3mm MIN
B	1.27mm +/-0.4mm

Packaging Specifications	
Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	250

Specifications	
Capacitance	0.047 uF
Measurement Condition	1 kHz 1.0Vrms
Capacitance Tolerance	5%
Voltage DC	1000 VDC
Dielectric Withstanding Voltage	1200 VDC
Temperature Range	-55/+125°C
Temperature Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor	0.1% 1kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	21.2766 GOhms

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